- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation**
- **Member of the Texas Instruments *Widebus*™ Family**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Supports Live Insertion**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages Using 25-mil Center-to-Center Spacings**

DGG OR DL PACKAGE
(TOP VIEW)

NC	1	56	GND
NC	2	55	NC
Y1	3	54	A1
GND	4	53	GND
Y2	5	52	A2
Y3	6	51	A3
V_{CC}	7	50	V_{CC}
Y4	8	49	A4
Y5	9	48	A5
Y6	10	47	A6
GND	11	46	GND
Y7	12	45	A7
Y8	13	44	A8
Y9	14	43	A9
Y10	15	42	A10
Y11	16	41	A11
Y12	17	40	A12
GND	18	39	GND
Y13	19	38	A13
Y14	20	37	A14
Y15	21	36	A15
V_{CC}	22	35	V_{CC}
Y16	23	34	A16
Y17	24	33	A17
GND	25	32	GND
Y18	26	31	A18
$\overline{OE}$	27	30	CLK
LE	28	29	GND

NC – No internal connection

description

The SN74LVT16835 is an 18-bit universal bus driver designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

Data flow from A to Y is controlled by the output-enable ($\overline{OE}$) input. This device operates in the transparent mode when the latch-enable (LE) input is high. The A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of the clock. When $\overline{OE}$ is high, the outputs are in the high-impedance state.
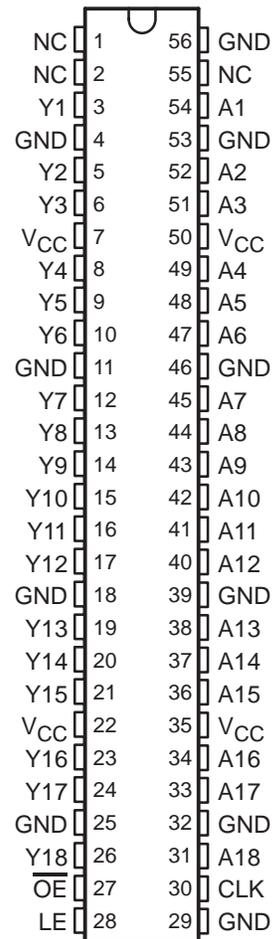
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVT16835 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the input/output (I/O) pins and functionality of standard small-outline packages in the same printed circuit board area.

The SN74LVT16835 is characterized for operation from –40°C to 85°C.

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TEXAS INSTRUMENTS

FUNCTION TABLE

INPUTS				OUTPUT
$\overline{OE}$	LE	CLK	A	Y
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	H	X	Y_0†
L	L	L	X	Y_0‡

† Output level before the indicated steady-state input conditions were established, provided that CLK was high before LE went low

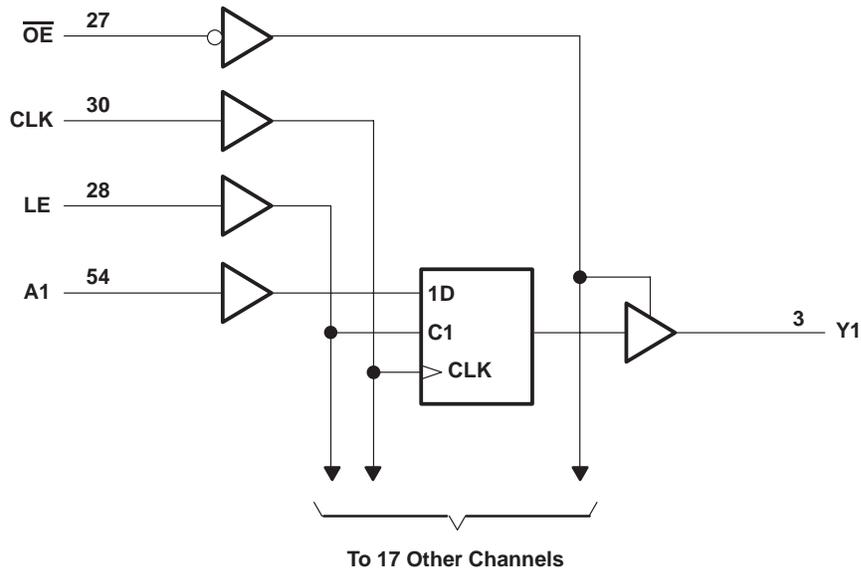‡ Output level before the indicated steady-state input conditions were established

logic symbol§
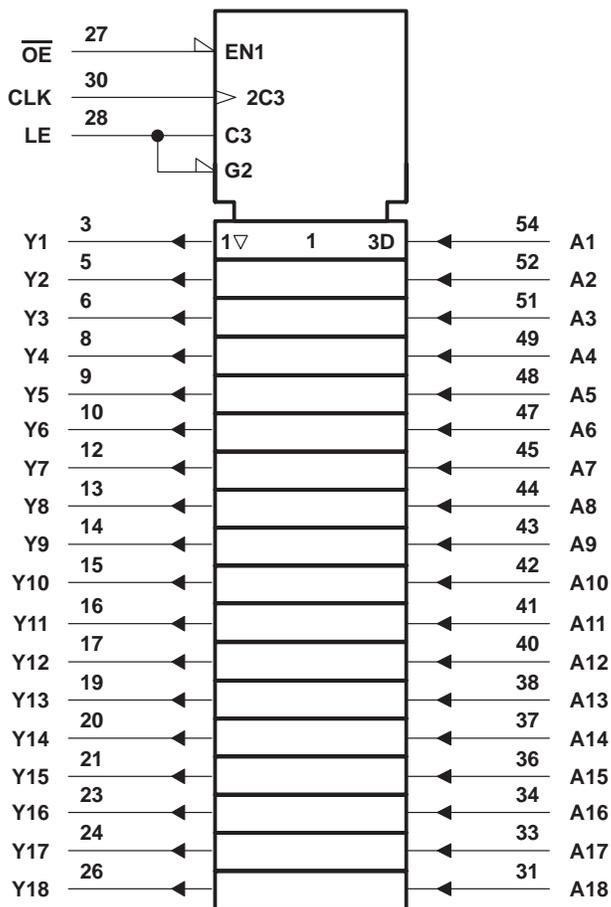
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

To 17 Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 4.6 V

Input voltage range, V_I (see Note 1) .... −0.5 V to 7 V

Voltage range applied to any output in the high state or power-off state, V_O (see Note 1) .... −0.5 V to 7 V

Current into any output in the low state, I_O .... 128 mA

Current into any output in the high state, I_O (see Note 2) .... 64 mA

Input clamp current, I_{IK} ($V_I < 0$) .... −50 mA

Output clamp current, I_{OK} ($V_O < 0$) .... −50 mA

Maximum power dissipation at T_A = 55°C (in still air) (see Note 3): DGG package .... 1 W

DL package .... 1.4 W

Operating free-air temperature range, T_A .... −40°C to 85°C

Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage			5.5	V
I_{OH}	High-level output current			−32	mA
I_{OL}	Low-level output current			64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 4:   Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[†]	MAX	UNIT
V_{IK}		V_{CC} = 2.7 V,	I_I = −18 mA			−1.2	V
V_{OH}		V_{CC} = 2.7 V to 3.6 V,	I_{OH} = −100 µA	V_{CC}−0.2			V
		V_{CC} = 2.7 V,	I_{OH} = −8 mA	2.4			
		V_{CC} = 3 V	I_{OH} = −32 mA	2			
V_{OL}		V_{CC} = 2.7 V	I_{OL} = 100 µA			0.2	V
			I_{OL} = 24 mA			0.5	
		V_{CC} = 3 V	I_{OL} = 16 mA			0.4	
			I_{OL} = 32 mA			0.5	
			I_{OL} = 64 mA			0.55	
I_I		V_{CC} = 0 or 3.6 V,	V_I = 5.5 V			10	µA
	Control inputs	V_{CC} = 3.6 V,	V_I = V_{CC} or GND			±1	
	A inputs	V_{CC} = 3.6 V	V_I = V_{CC}			1	
			V_I = 5.5 V			20	
			V_I = 0			−5	
I_{off}		V_{CC} = 0,	V_I or V_O = 0 to 4.5 V			±100	µA
$I_{I(hold)}$	A inputs	V_{CC} = 3 V	V_I = 0.8 V	75			µA
			V_I = 2 V	−75			
I_{OZH}		V_{CC} = 3.6 V,	V_O = 3 V			1	µA
I_{OZL}		V_{CC} = 3.6 V,	V_O = 0.5 V			−1	µA
I_{CC}		V_{CC} = 3.6 V, V_I = V_{CC} or GND	I_O = 0, Outputs high			0.12	mA
			Outputs low			5	
			Outputs disabled			0.12	
ΔI_{CC}[‡]		V_{CC} = 3 V to 3.6 V, Other inputs at V_{CC} or GND	One input at V_{CC} − 0.6 V,			0.2	mA
C_i	Control inputs	V_I = 3 V or 0			3.5		pF
	Data pins				4.5		
C_o		V_O = 3 V or 0			11		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

TEXAS
INSTRUMENTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V_{CC} = 3.3 V ± 0.3 V		V_{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	150	0	125	MHz
t_w	Pulse duration	LE high	3.3		3.3		ns
		CLK high or low	3.3		3.3		
t_{su}	Setup time	Data before CLK↑	1.6		2.1		ns
		Data before LE↓, CLK high	2.6		1.9		
		Data before LE↓, CLK low	2		1.3		
t_h	Hold time	Data after CLK↑	2		2.1		ns
		Data after LE↓	0.9		1.2		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V ± 0.3 V			V_{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
f_{max}			150			150		MHz
t_{PLH}	A	Y	1.7	3	5.4		6.8	ns
t_{PHL}			1.6	3.2	5.9		7.7	
t_{PLH}	LE	Y	2.3	4	7		8.5	ns
t_{PHL}			2.7	4.3	7.9		9.7	
t_{PLH}	CLK	Y	2.5	4.1	7.9		9.2	ns
t_{PHL}			3.5	5.4	8.9		10.4	
t_{PZH}	$\overline{OE}$	Y	1.2	3	5		5.9	ns
t_{PZL}			1.5	3	5.8		6.9	
t_{PHZ}	$\overline{OE}$	Y	2.7	4.6	7.4		8.3	ns
t_{PLZ}			2.8	4.7	6.7		7.2	

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION
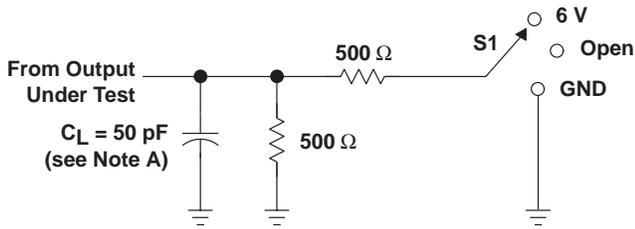
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT
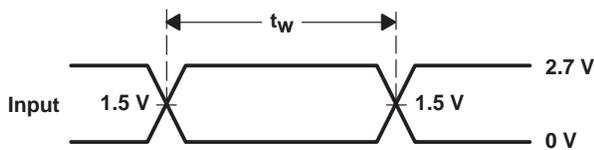
VOLTAGE WAVEFORMS
PULSE DURATION
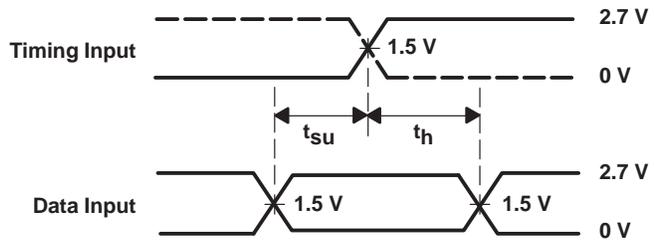
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES
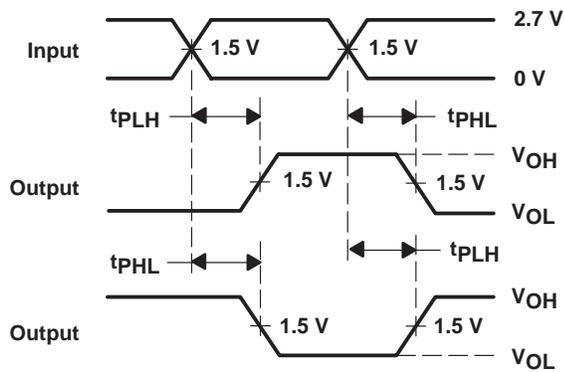
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS
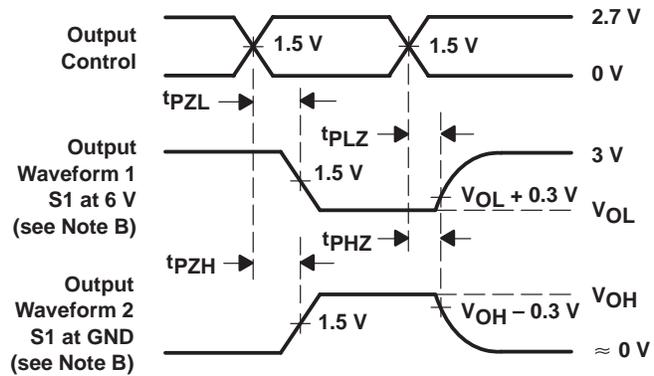
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74LVT16835DGGRE4	NRND	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVT16835DGGRG4	NRND	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16835DGGR	NRND	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16835DL	NRND	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVT16835DLR	NRND	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers
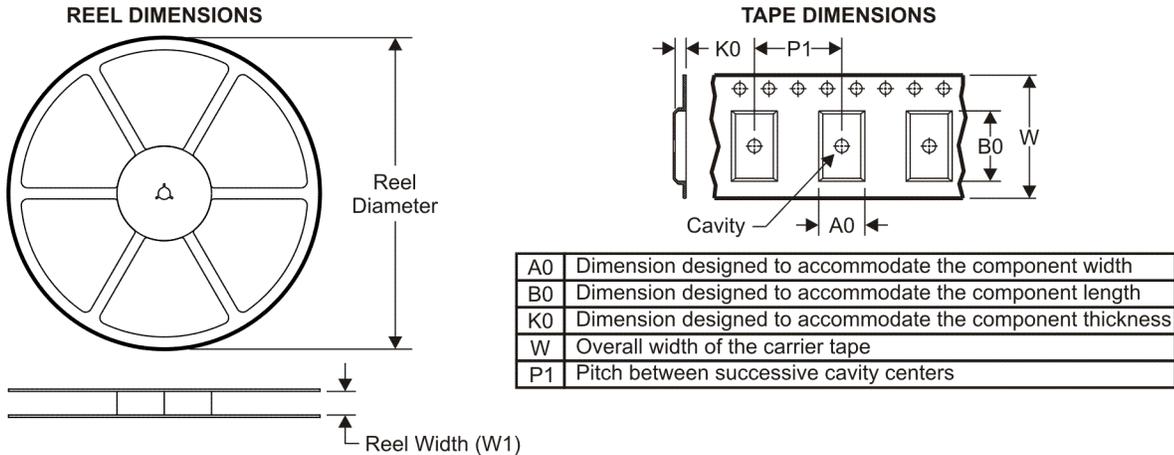
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE
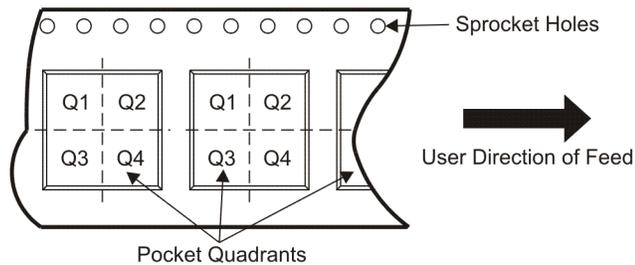
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVT16835DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVT16835DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS
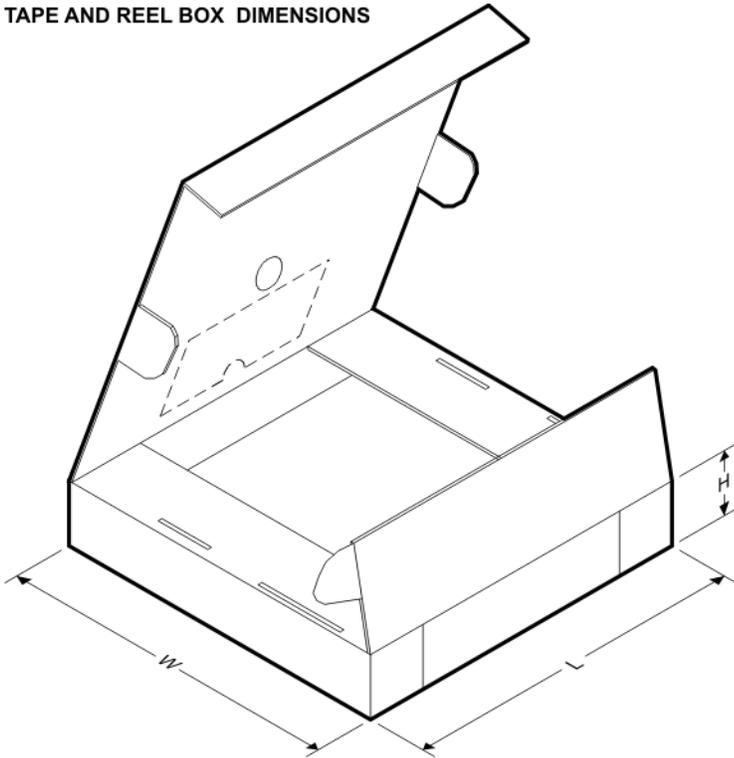
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVT16835DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74LVT16835DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078/F 12/97
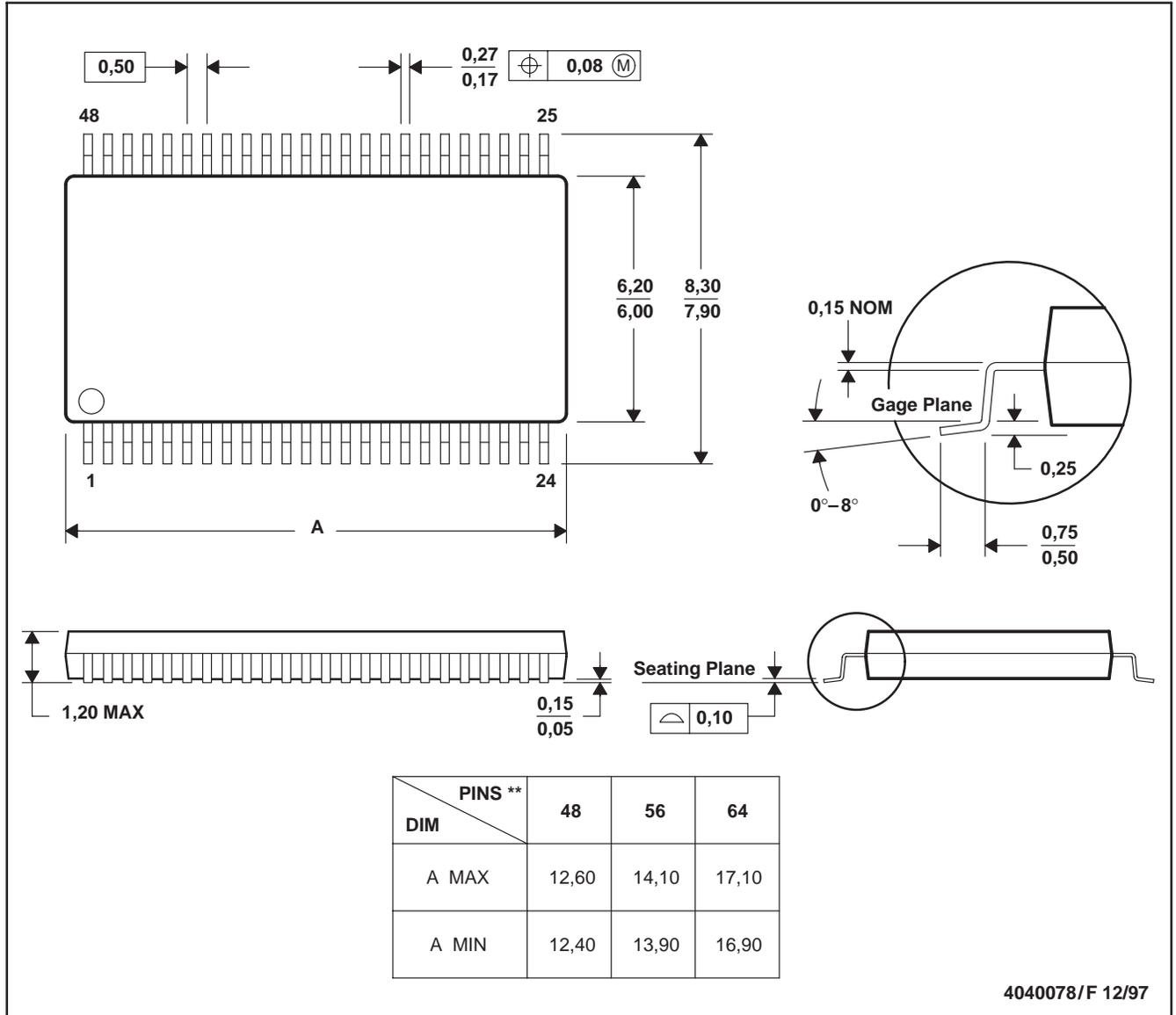
NOTES: A. All linear dimensions are in millimeters.
      B. This drawing is subject to change without notice.
      C. Body dimensions do not include mold protrusion not to exceed 0,15.
      D. Falls within JEDEC MO-153

DL (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048 / E 12/01
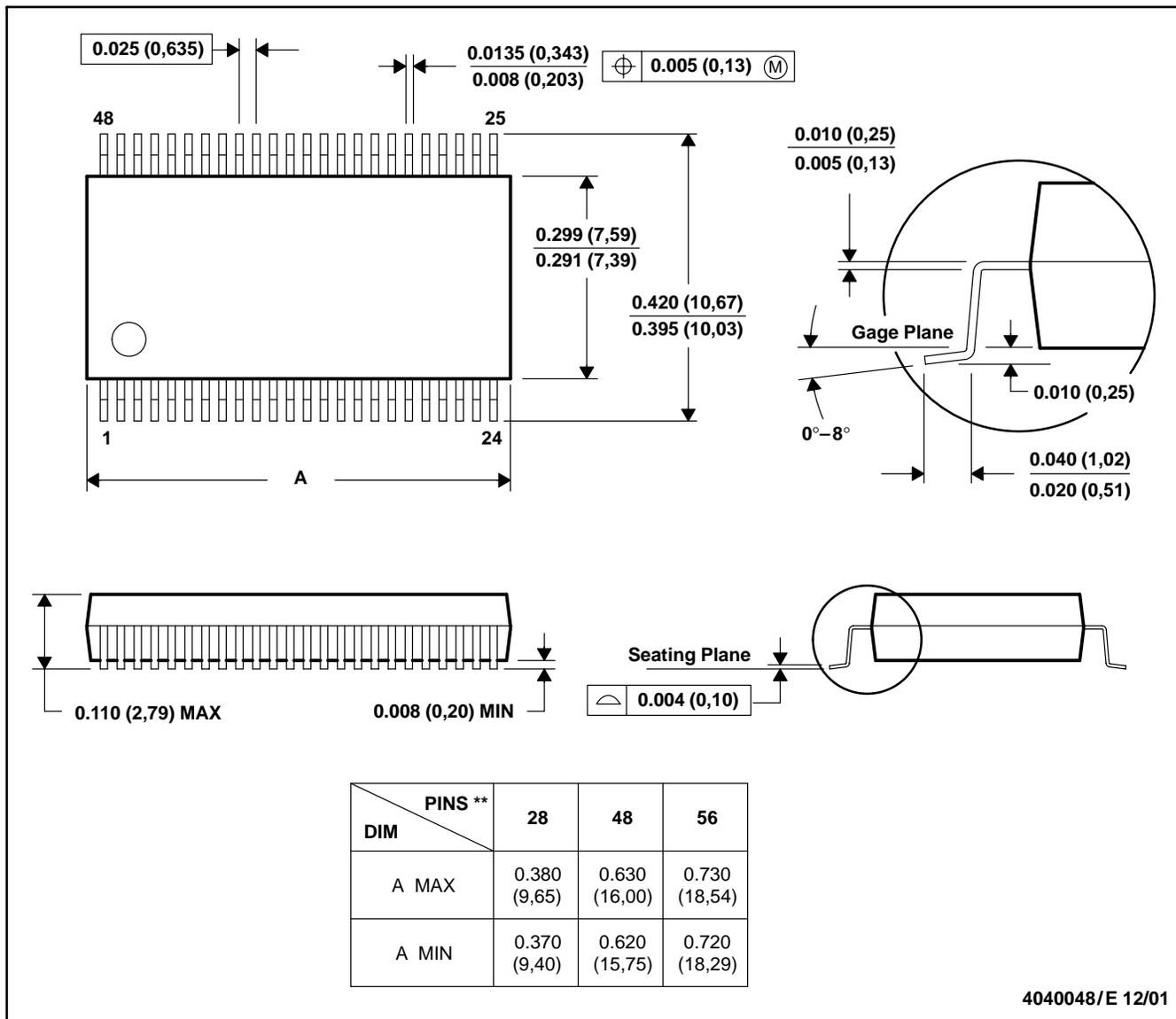
NOTES: A. All linear dimensions are in inches (millimeters).
             B. This drawing is subject to change without notice.
             C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
             D. Falls within JEDEC MO-118

IMPORTANT NOTICE